



Material Content Data Sheet



Sales Product Name	TLE8209-4SA			Issued		28. August 2013		
MA#	MA001024936							
Package	PG-DSO-20-65			Weight*		2028.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.895	0.54	0.54	5370	5370
leadframe	inorganic material	phosphorus	7723-14-0	0.359	0.02		177	
	non noble metal	zinc	7440-66-6	1.435	0.07		707	
	non noble metal	iron	7439-89-6	28.697	1.41		14144	
	non noble metal	copper	7440-50-8	1165.200	57.44	58.94	574307	589335
wire	non noble metal	copper	7440-50-8	2.734	0.13	0.13	1348	1348
encapsulation	organic material	carbon black	1333-86-4	1.598	0.08		788	
	plastics	epoxy resin	-	73.508	3.62		36231	
	inorganic material	silicondioxide	60676-86-0	723.891	35.68	39.38	356793	393812
leadfinish	non noble metal	tin	7440-31-5	10.336	0.51	0.51	5094	5094
plating	noble metal	silver	7440-22-4	0.686	0.03	0.03	338	338
solder	noble metal	silver	7440-22-4	0.143	0.01		71	
	non noble metal	tin	7440-31-5	0.095	0.00		47	
	non noble metal	lead	7439-92-1	9.303	0.46	0.47	4585	4703
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

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